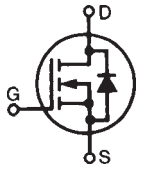
IXYS

HiperFET™ Power MOSFETs Q-Class

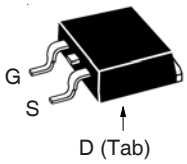
IXFA4N100Q
IXFP4N100Q

V_{DSS} = 1000V
I_{D25} = 4A
$R_{DS(on)}$ ≤ 3.0Ω

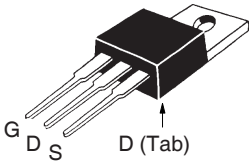
N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Diode



TO-263 AA (IXFA)



TO-220AB (IXFP)



G = Gate D = Drain
S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C	1000	V
V_{DGR}	T_J = 25°C to 150°C, R_{GS} = 1MΩ	1000	V
V_{GSS}	Continuous	± 20	V
V_{GSM}	Transient	± 30	V
I_{D25}	T_C = 25°C	4	A
I_{DM}	T_C = 25°C, Pulse Width Limited by T_{JM}	16	A
I_A	T_C = 25°C	4	A
E_{AS}	T_C = 25°C	700	mJ
dv/dt	$I_S \le I_{DM}$, $V_{DD} \le V_{DSS}$, $T_J \le 150°C$	5	V/ns
P_D	T_C = 25°C	150	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	Plastic Body for 10s	260	°C
M_C	Mounting Force (TO-263)	10..65/2.2..14.6	Nm/lb.in.
M_d	Mounting Torque (TO-220)	1.13/10	Nm/lb.in.
Weight	TO-263	2.5	g
	TO-220	3.0	g

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 1mA	1000			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 1.5mA	2.5		4.5	V
I_{GSS}	V_{GS} = ± 20V, V_{DS} = 0V			± 100	nA
I_{DSS}	$V_{DS} = V_{DSS}$, V_{GS} = 0V			50	μA
	T_J = 125°C			1	mA
$R_{DS(on)}$	V_{GS} = 10V, $I_D = 0.5 \bullet I_{D25}$, Note 1			3.0	Ω

Features

- International Standard Packages
- Avalanche Rated
- Fast Intrinsic Diode
- Low Q_G
- Low $R_{DS(on)}$
- Low Drain-to-Tab Capacitance
- Low Package Inductance

Advantages

- High Power Density
- Easy to Mount
- Space Savings

Applications

- DC-DC Converters
- Battery Chargers
- Switch-Mode and Resonant-Mode Power Supplies
- DC Choppers
- Temperature and Lighting Controls

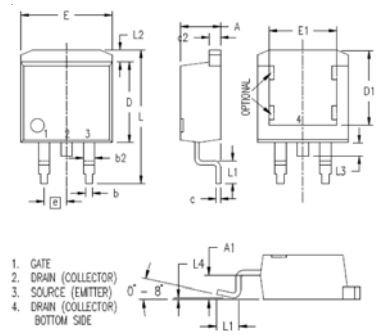
Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = 20V, I_D = 0.5 • I_{D25}, Note 1	1.5	2.5		S
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		1050		pF
C_{oss}			120		pF
C_{rss}			30		pF
$t_{d(on)}$	**Resistive Switching Times**		17		ns
t_r	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		15		ns
$t_{d(off)}$	R_G = 4.7Ω (External)		32		ns
t_f			18		ns
$Q_{g(on)}$	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		39		nC
Q_{gs}			9		nC
Q_{gd}			23		nC
R_{thJC}				0.80	°C/W
R_{thCS}	TO-220		0.50		°C/W

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			4	A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			16	A
V_{SD}	I_F = I_S, V_{GS} = 0V, Note 1			1.5	V
t_{rr}	I_F = I_S, -di/dt = 100A/μs			250	ns
Q_{RM}	V_R = 100V, V_{GS} = 0V		0.52		μC
I_{RM}			1.80		A

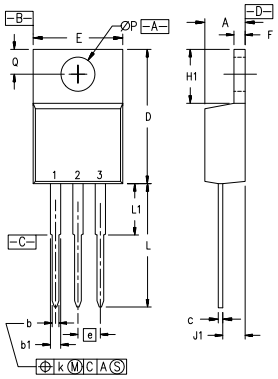
Note 1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.

TO-263 Outline



SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.160	.190	4.06	4.83
A1	.080	.110	2.03	2.79
b	.020	.039	0.51	0.99
b2	.045	.055	1.14	1.40
c	.016	.029	0.40	0.74
c2	.045	.055	1.14	1.40
D	.340	.380	8.64	9.65
D1	.315	.350	8.00	8.89
E	.380	.410	9.65	10.41
E1	.245	.320	6.22	8.13
e	.100 BSC		2.54 BSC	
L	.575	.625	14.61	15.88
L1	.090	.110	2.29	2.79
L2	.040	.055	1.02	1.40
L3	.050	.070	1.27	1.78
L4	0	.005	0	0.13

TO-220 Outline



Pins: 1 - Gate 2 - Drain
3 - Source

SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.170	.190	4.32	4.83
b	.025	.040	0.64	1.02
b1	.045	.065	1.15	1.65
c	.014	.022	0.35	0.56
D	.580	.630	14.73	16.00
E	.390	.420	9.91	10.66
e	.100 BSC		2.54 BSC	
F	.045	.055	1.14	1.40
H1	.230	.270	5.85	6.85
J1	.090	.110	2.29	2.79
k	0	.015	0	0.38
L	.500	.550	12.70	13.97
L1	.110	.230	2.79	5.84
ØP	.139	.161	3.53	4.08
Q	.100	.125	2.54	3.18

Figure 1. Output Characteristics at 25°C

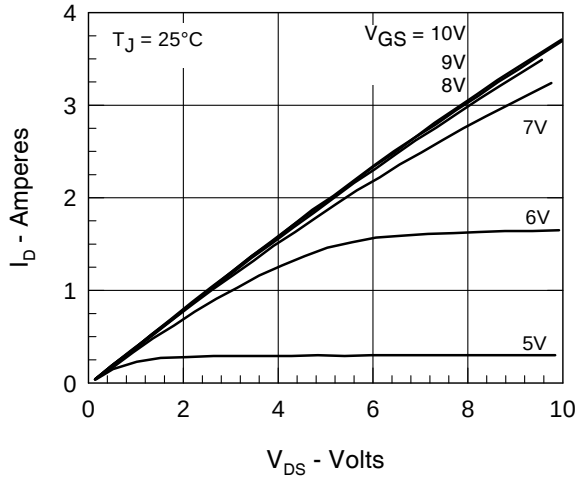


Figure 2. Extended Output Characteristics at 125°C

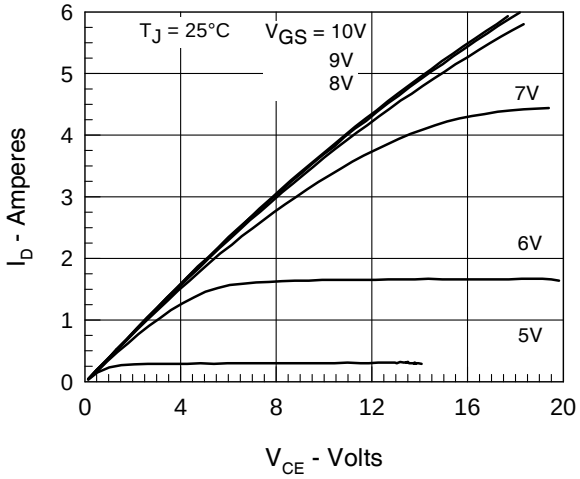


Figure 3. Output characteristics at 125°C

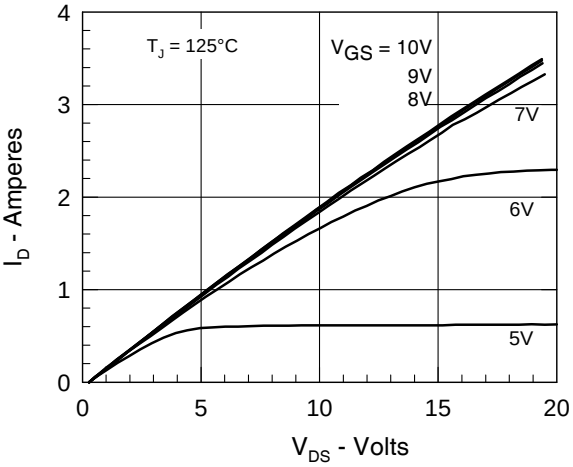


Figure 4. Admittance Curves

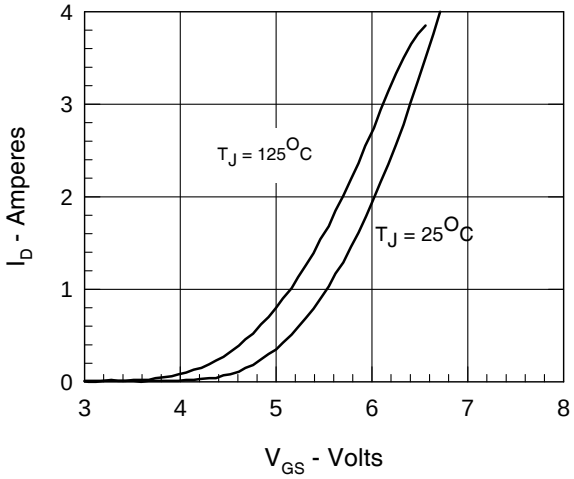


Figure 5. $R_{DS(on)}$ normalized to 0.5 I_{D25} value vs. I_D

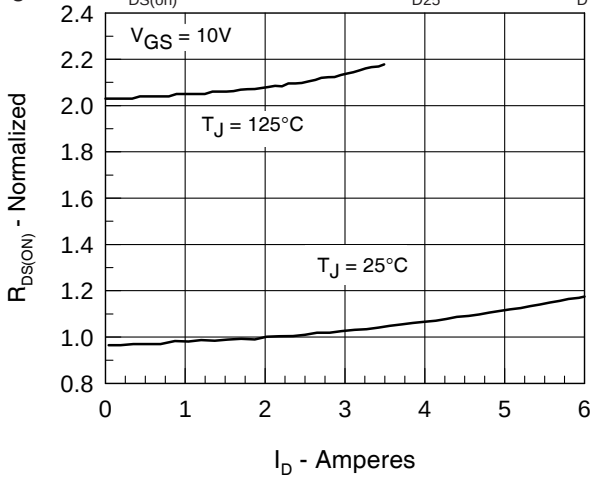


Figure 6. $R_{DS(on)}$ normalized to 0.5 I_{D25} value vs. T_J

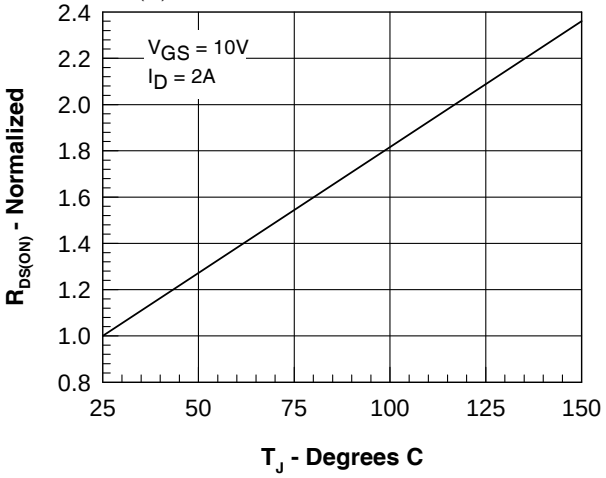


Figure 7. Gate Charge

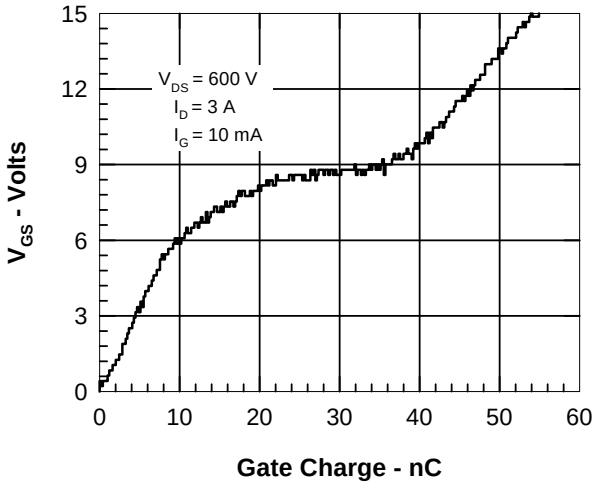


Figure 8. Capacitance Curves

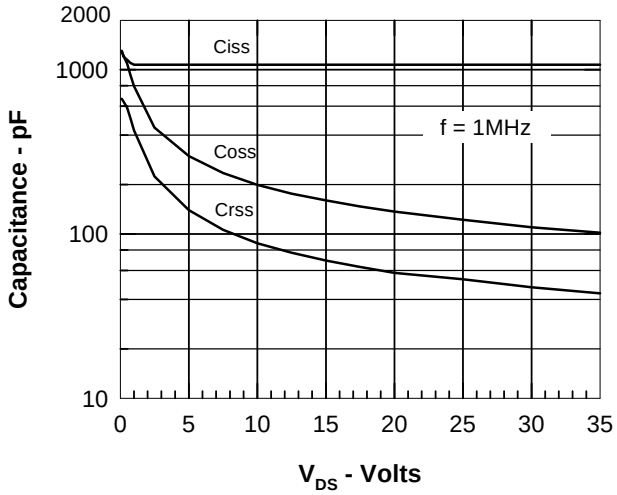
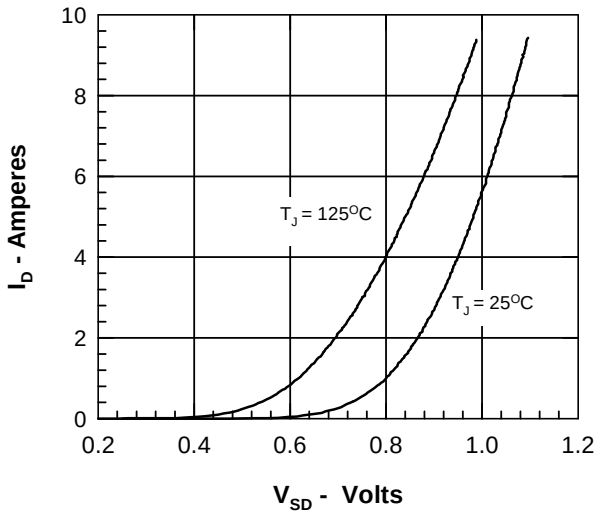


Figure 9. Forward Voltage Drop of the Intrinsic Diode



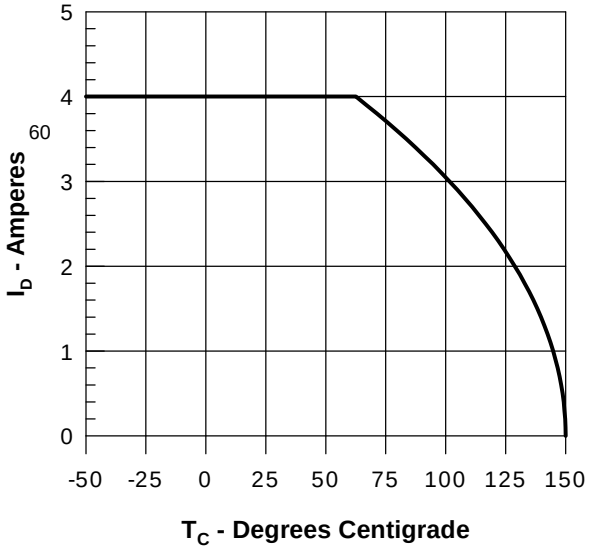


Figure 11. Transient Thermal Resistance